

RELIABILITY REPORT FOR

DS1411, Rohs Compliant

Dallas Semiconductor

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Prepared by:

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Conclusion:

The following qualification successfully meets the quality and reliability standards required of all Dallas Semiconductor products and processes:

In addition, Dallas Semiconductor's continuous reliability monitor program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards. The current status of the reliability monitor program can be viewed at http://www.maxim-ic.com/TechSupport/dsreliability.html.*

Module Description

A description of this Module can be found in the product data sheet. You can find the product data sheet at http://dbserv.maxim-ic.com/l_datasheet3.cfm.*

Reliability Derating:

A module device consists of one or more IC's in a single, upward integrated, package. This package is assembled to include batteries, crystals, and other piece parts that make up the configuration of the Module. Because of either the complexity of the package or the included piece parts, standard high temperature reliability testing is not possible. Therefore, in order to determine the reliability of module products, the reliability of each of the piece parts is individually determined, then summed to determine the reliability of the integrated module product. If there are "n" significant components in the module then:

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Fr (module) = Fr (1) + Fr (2) + Fr (3) + ..... + Fr (n)
Fr (module) = Failure rate of module
Fr(n) = Failure rate of the nth component
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Failure Rates are reported in FITs (Failures in Time) or MTTF (Mean Time To Failure). The FIT rate is related to MTTF by:

MTTF = 1/Fr

NOTE: MTTF is frequently used interchangeably with MTBF.

The calculated failure rate for this module/assembly is:

Module Device:	Module Units:	Quantity:	Fails:	<u>Ea:</u>	Beta:	MTTF (Yrs):	FITs:
DS1481	1	7070	0	0.7	0.0	362411	0.3
DS2401	1	2323	0	0.7	0.0	94291	1.2
Totals:						74823	1.5

The parameters used to calculate the module failure rate are as follows

Cf: 60% Tu: 25 °C Vu: 5.5 Volts

The reliability data follows. At the start of this data is the module assembly information. This is a description of the module. The next section is the detailed reliability data for each stress found in the qualification / monitor. If there are additional processes or assemblies used as part of this report, a description of each will follow which includes the respective reliability data for that process/ assembly. The reliability data section includes the latest data available. Some of this data may be generic with other packages or products.

* Some proprietary products may be excepted from this requirement

Assembly Information:

Assembly Site: Fastech

Pin Count: 0

Package Type: Dongle or Fob (RoHS)

Body Size: 0 Mold Compound: NA

Lead Frame: PCB; FR4
Lead Finsh: Sn Dip 100%

Die Attach: ?
Bond Wire / Size: /

Flammability: UL 94-V0

Moisture Sensitivity (JEDEC J-STD20A)

Date Code Range: 0619 to 0619

Date Code Range:		0619 to 061	619			
STORAGE LIFE						
DESCRIPTION	DATE CD	CONDITION	READ	POINT QTY	FAILS	FA#
STORAGE LIFE	0619	85 C	1000	HRS 77	0	
				Total:	0	
TEMPERATURE CY	YCLE					
DESCRIPTION	DATE CD	CONDITION	READ	POINT QTY	FAILS	FA#
TEMP CYCLE	0619	-40 TO 85C	1000	CYS 77	0	
				Total:	0	
UNBIASED MOIST	URE RESIST	ANCE				
DESCRIPTION	DATE CD	CONDITION	READ	POINT QTY	FAILS	FA#
MOISTURE SOAK	0619	60C/90% R.H.	1000	HRS 77	0	
				Total:	0	
STORAGE LIFE						
DESCRIPTION	DATE CD	CONDITION	READ	POINT QTY	FAILS	FA#
STORAGE LIFE	0619	85 C	1000	HRS 77	0	
				Total:	0	
TEMPERATURE CY	YCLE					
DESCRIPTION	DATE CD	CONDITION	READ	POINT QTY	FAILS	FA#
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				Total:	0	
STORAGE LIFE						
DESCRIPTION	DATE CD	CONDITION	READ	POINT QTY	FAILS	FA#

STORAGE LIFE	0619	85 C	1000	HRS	77	0	
				Total:		0	
TEMPERATURE C	YCLE						
DESCRIPTION	DATE C	CONDITION	READ	POINT	QTY	FAILS	FA#
TEMP CYCLE	0619	-40 TO 85C	1000	CYS	77	0	
			Total:		0		
UNBIASED MOIST	JRE RESIS	TANCE					
DESCRIPTION	DATE C	CONDITION	READ	POINT	QTY	FAILS	FA#
MOISTURE SOAK	0619	60C/90% R.H.	1000	HRS	77	0	
				Total:		0	